

MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

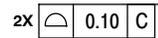
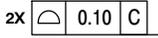
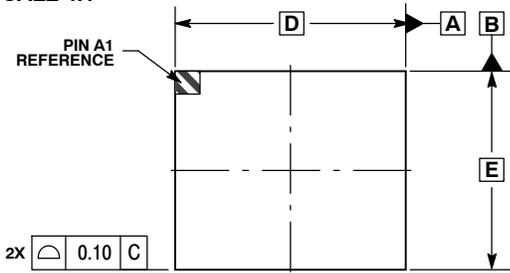
ON Semiconductor®



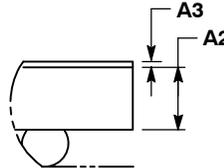
25 Pin Flip-Chip, 2.55x2.20 CASE 499BN ISSUE A

DATE 26 OCT 2011

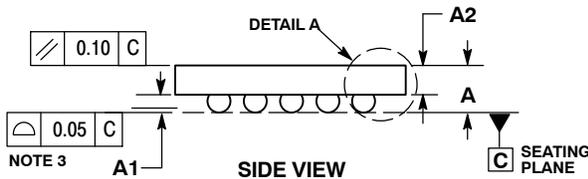
SCALE 4:1



TOP VIEW

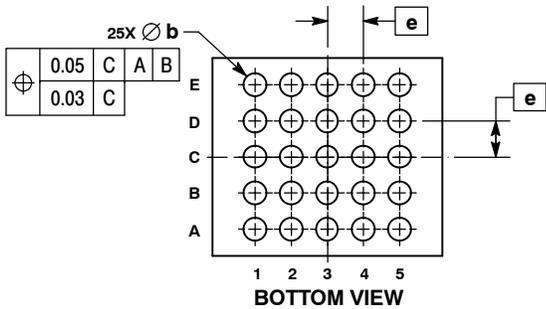


DETAIL A



NOTE 3

SIDE VIEW



BOTTOM VIEW

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

DIM	MILLIMETERS	
	MIN	MAX
A	---	0.60
A1	0.17	0.23
A2	0.36 REF	
A3	0.04 REF	
b	0.24	0.29
D	2.55 BSC	
E	2.20 BSC	
e	0.40 BSC	

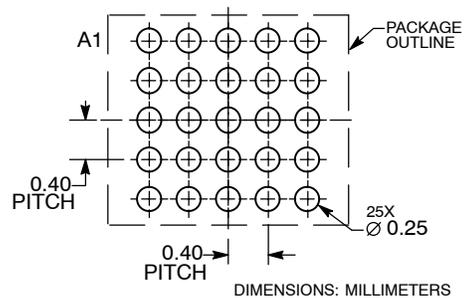
GENERIC MARKING DIAGRAM*



- XXXXXX = Specific Device Code
- A = Assembly Location
- Y = Year
- WW = Work Week
- = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

RECOMMENDED SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION:	25 PIN FLIP-CHIP, 2.55X2.20	PAGE 1 OF 2

